

PCN Number:	20160411001	PCN Date:	04/11/2016
Title:	Datasheet for DDA0008J Package Drawing update		
Customer Contact:	PCN Manager	Dept:	Quality Services
Change Type:			
<input type="checkbox"/> Assembly Site	<input type="checkbox"/> Design	<input type="checkbox"/> Wafer Bump Site	
<input type="checkbox"/> Assembly Process	<input checked="" type="checkbox"/> Data Sheet	<input type="checkbox"/> Wafer Bump Material	
<input type="checkbox"/> Assembly Materials	<input type="checkbox"/> Part number change	<input type="checkbox"/> Wafer Bump Process	
<input type="checkbox"/> Mechanical Specification	<input type="checkbox"/> Test Site	<input type="checkbox"/> Wafer Fab Site	
<input type="checkbox"/> Packing/Shipping/Labeling	<input type="checkbox"/> Test Process	<input type="checkbox"/> Wafer Fab Materials	
		<input type="checkbox"/> Wafer Fab Process	

Notification Details

Description of Change:

Texas Instruments Incorporated is announcing an information only notification. The product datasheet(s) is being update to Update DDA0008J Package Drawing.

Devices Affected:

HPA00295DDAR, TPS5430DDA, TPS5430DDA-P, TPS5430DDAG4, TPS5430DDAR, TPS5430DDAR-P, TPS5430DDARG4, TPS5431DDA, TPS5431DDAG4, TPS5431DDAR, TPS5431DDARG4, TPS56527DDA, TPS56527DDAR.

Package Outline:

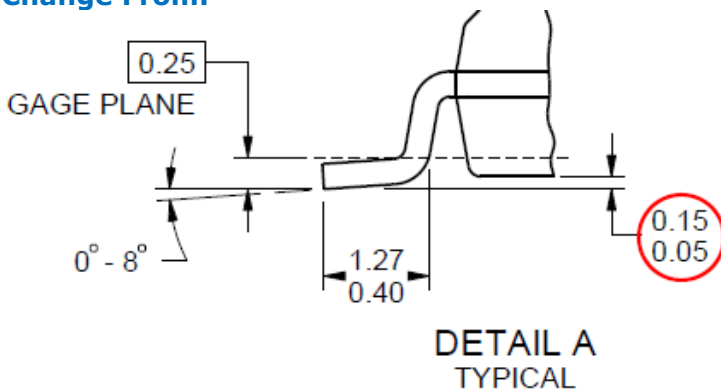
- DDA0008J 4221637 rev A to B

Drawing Changes:

1. Minimum Standoff Height

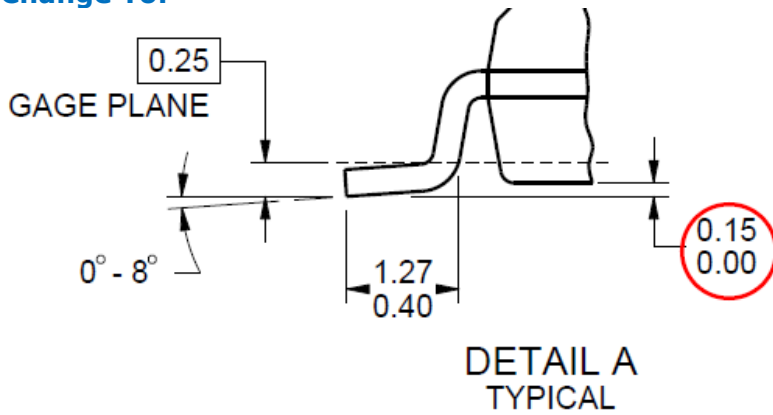
Drawing is being revised to correct a typo on the minimum value of the standoff which was inadvertently changed when the drawing was reformatted. It is now being reset to prior value which conforms to JEDEC Registration MS-012F

Change From:



4221637/A 09/2014

Change To:



4221637/B 03/2016

2. Minimum Dimensions Thermal Pad

Thermal pad MIN dimensions are being modified to properly reflect the dimensions across our multiple manufacturing sources:

Long side: From 2.9mm MIN to 2.5mm MIN

Short side: From 2.4mm MIN to 2.0mm MIN

The updated datasheet(s) can be accessed at www.ti.com

Reason for Change:

To more accurately reflect device characteristics.

Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):

There is no physical change to the packages; this is updating the documentation to match the parts. This change should have no effect on PCB designs as the land pattern should be designed to accommodate the MAX dimensions which have not changed. There are no changes to the board layout and stencil design examples.

Changes to product identification resulting from this PCN:

None.

Product Affected:

HPA00295DDAR	TPS5430DDAR	TPS5431DDA	TPS5431DDARG4
TPS5430DDA	TPS5430DDARG4	TPS5431DDAG4	TPS56527DDA
TPS5430DDAG4	TPS5430DDAR-P	TPS5431DDAR	TPS56527DDAR
TPS5430DDA-P			

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
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